

In The Claims:

1. (Cancelled).
2. (Cancelled).
3. (Previously Presented) A hermetic seal for an electronic circuit die comprising:
  - an inorganic layer for preventing moisture from reaching the electronic circuit die;
  - an organic layer outside the inorganic layer for protecting the inorganic layer; and
  - a plastic package.
4. (Original) The apparatus of claim 3 wherein the inorganic layer is outside the plastic package.
5. (Original) The apparatus of claim 4 wherein the inorganic layer is inside the plastic package.
6. (Previously Presented) A hermetic seal for an electronic circuit die comprising:
  - an inorganic layer for preventing moisture from reaching the electronic circuit die;
  - an organic layer outside the inorganic layer for protecting the inorganic layer;
  - a lead; and
  - a wire; wherein the inorganic layer contacts the lead.
7. (Cancelled).

8. (Previously Presented) A hermetic seal for an electronic circuit die comprising:

an inorganic layer for preventing moisture from reaching the electronic circuit die; and

an organic layer outside the inorganic layer for protecting the inorganic layer, the organic layer comprising a material consisting of para-xylylene, hybrid solgel, and polymeric materials.

9-14. (Cancelled).

15. (Previously Presented) A hermetically sealed device comprising:

an electronic circuit die;

an inorganic layer outside the electronic circuit die;

an organic layer outside the inorganic material;

a wire; and

a lead; wherein the inorganic layer contacts the lead.

16. (Cancelled).

17. (Previously Presented) A hermetically sealed device comprising:

an electronic circuit die;

an inorganic layer outside the electronic circuit die; and

an organic layer outside the inorganic material, the organic layer comprises comprising a material consisting of para-xylylene, hybrid solgel, and polymeric materials.

- 18: (Previously Presented) A hermetically sealed device comprising:  
an electronic circuit die;  
an inorganic layer outside the electronic circuit die;  
an organic layer outside the inorganic material;  
a wire;  
a lead; and  
a plastic package.
19. (Original) The hermetically sealed device of claim 18 wherein the plastic package contacts the inorganic layer.
20. (Original) The hermetically sealed device of claim 18 wherein the plastic package contacts the organic layer.
21. (Cancelled).